

CY74FCT652T
8-BIT REGISTERED TRANSCEIVER
WITH 3-STATE OUTPUTS

SCCS032B – SEPTEMBER 1994 – REVISED OCTOBER 2001

ORDERING INFORMATION

TA	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	5.4	CY74FCT652CTQCT	FCT652C
	SOIC – SO	Tube	5.4	CY74FCT652CTSOC	FCT652C
		Tape and reel	5.4	CY74FCT652CTSOCT	
	QSOP – Q	Tape and reel	6.3	CY74FCT652ATQCT	FCT652A
	SOIC – SO	Tube	6.3	CY74FCT652ATSOC	FCT652A
		Tape and reel	6.3	CY74FCT652ATSOCT	
QSOP – Q	Tape and reel	9	CY74FCT652TQCT	FCT652	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION
GAB	$\overline{\text{GBA}}$	CPAB	CPBA	SAB	SBA	A ₁ –A ₈	B ₁ –B ₈	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified§	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified§	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	Input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
H	H	X	X	L	X	Input	Output	Real-time A data to B bus
H	H	H or L	X	H	X	Input	Output	Stored A data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored A data to B bus and Stored B data to A bus

H = High logic level, L = Low logic level, X = Don't care, ↑ = Low-to-high transition

‡ Select control = L: clocks can occur simultaneously. Select control = H: clocks must be staggered in order to load both registers.

§ The data output functions can be enabled or disabled by various signals at the GAB and $\overline{\text{GBA}}$ inputs. Data input functions always are enabled, i.e., data at the bus pins are stored on every low-to-high transition of the clock inputs.



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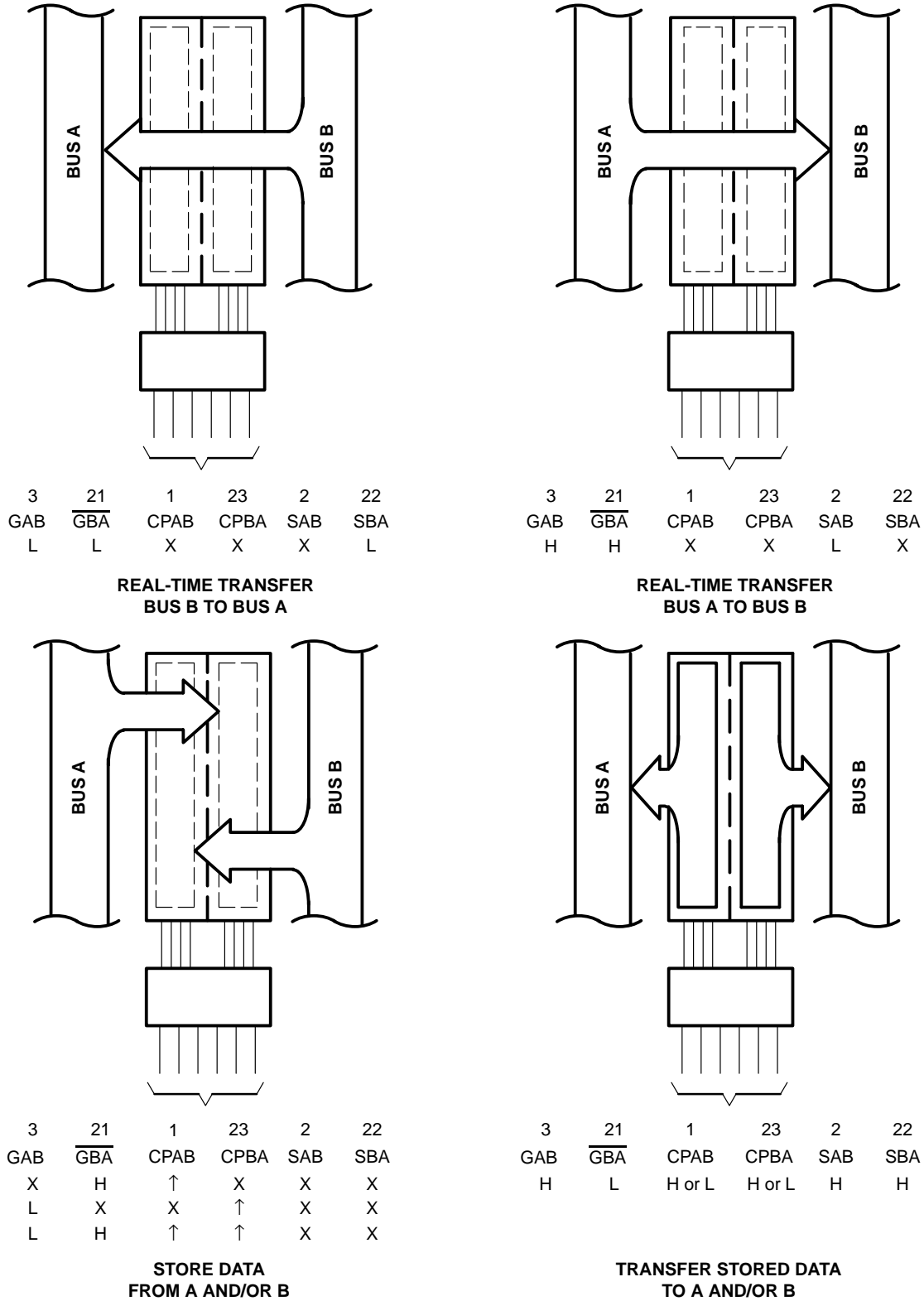


Figure 1. Bus-Management Functions

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	61°C/W
SO package	46°C/W
Ambient temperature range with power applied, T_A	–65°C to 135°C
Storage temperature range, T_{Stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.75	5	5.25	V
V_{IH} High-level input voltage	2			V
V_{IL} Low-level input voltage			0.8	V
I_{OH} High-level output current			–32	mA
I_{OL} Low-level output current			64	mA
T_A Operating free-air temperature	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	$V_{CC} = 4.75\text{ V}$,	$I_{IN} = -18\text{ mA}$		-0.7	-1.2	V
V_{OH}	$V_{CC} = 4.75\text{ V}$	$I_{OH} = -32\text{ mA}$		2		V
		$I_{OH} = -15\text{ mA}$	2.4	3.3		
V_{OL}	$V_{CC} = 4.75\text{ V}$,	$I_{OL} = 64\text{ mA}$		0.3	0.55	V
V_{hys}	All inputs			0.2		V
I_I	$V_{CC} = 5.25\text{ V}$,	$V_{IN} = V_{CC}$			5	μA
I_{IH}	$V_{CC} = 5.25\text{ V}$,	$V_{IN} = 2.7\text{ V}$			± 1	μA
I_{IL}	$V_{CC} = 5.25\text{ V}$,	$V_{IN} = 0.5\text{ V}$			± 1	μA
I_{OZH}	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 2.7\text{ V}$			10	μA
I_{OZL}	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 0.5\text{ V}$			-10	μA
I_{OS}^\ddagger	$V_{CC} = 5.25\text{ V}$,	$V_{OUT} = 0\text{ V}$	-60	-120	-225	mA
I_{off}	$V_{CC} = 0\text{ V}$,	$V_{OUT} = 4.5\text{ V}$			± 1	μA
I_{CC}	$V_{CC} = 5.25\text{ V}$,	$V_{IN} \leq 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$		0.1	0.2	mA
ΔI_{CC}	$V_{CC} = 5.25\text{ V}$, $V_{IN} = 3.4\text{ V}^\S$, $f_1 = 0$, Outputs open			0.5	2	mA
I_{CCD}^\parallel	$V_{CC} = 5.25\text{ V}$, One input switching at 50% duty cycle, Outputs open, GAB or GBA = GND, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$			0.06	0.12	mA/MHz
$I_C^\#$	$V_{CC} = 5.25\text{ V}$, $f_0 = 10\text{ MHz}$, Outputs open, GAB = GBA = GND, SAB = CPAB = GND, SBA = V_{CC}	One bit switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$	0.7	1.4	mA
			$V_{IN} = 3.4\text{ V}$ or GND	1.2	3.4	
		Eight bits switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$	2.8	5.6	
			$V_{IN} = 3.4\text{ V}$ or GND	5.1	14.6	
C_i				5	10	pF
C_o				9	12	pF

† Typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input ($V_{IN} = 3.4\text{ V}$); all other inputs at V_{CC} or GND

¶ This parameter is derived for use in total power-supply calculations.

$$\# I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4\text{ V}$)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		CY74FCT652T		CY74FCT652AT		CY74FCT652CT		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, clock high or low	6		5		5		ns
t_{su}	Setup time, before CPAB \uparrow or CPBA \uparrow	A or B		4		2		ns
t_h	Hold time, after CPAB \uparrow or CPBA \uparrow	A or B		2		1.5		ns

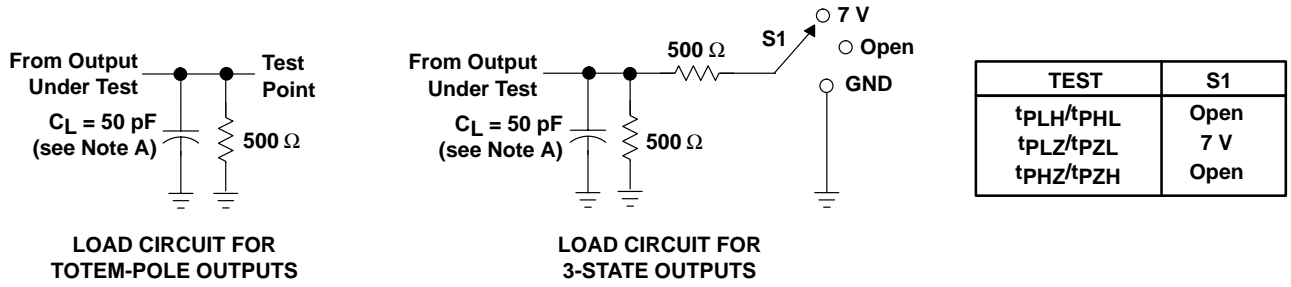
switching characteristics over operating free-air temperature range (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT652T		CY74FCT652AT		CY74FCT652CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	9	1.5	6.3	1.5	5.4	ns
t_{PHL}			1.5	9	1.5	6.3	1.5	5.4	
t_{PZH}	GAB or \overline{GBA}	A or B	1.5	14	1.5	9.8	1.5	7.8	ns
t_{PZL}			1.5	14	1.5	9.8	1.5	7.8	
t_{PHZ}	GAB or \overline{GBA}	A or B	1.5	9	1.5	6.3	1.5	6.3	ns
t_{PLZ}			1.5	9	1.5	6.3	1.5	6.3	
t_{PLH}	CPAB or CPBA	A or B	1.5	9	1.5	6.3	1.5	5.7	ns
t_{PHL}			1.5	9	1.5	6.3	1.5	5.7	
t_{PLH}	SBA or SAB	A or B	1.5	11	1.5	7.7	1.5	6.2	ns
t_{PHL}			1.5	11	1.5	7.7	1.5	6.2	

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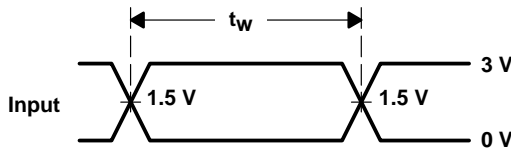
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PARAMETER MEASUREMENT INFORMATION

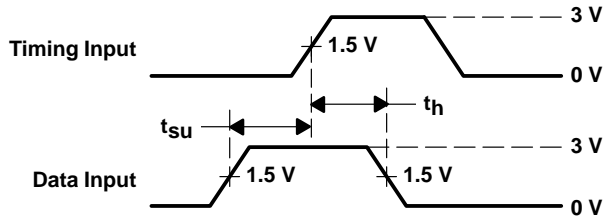


LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

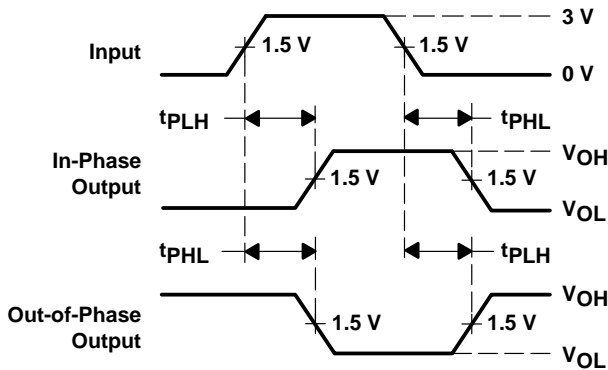
LOAD CIRCUIT FOR 3-STATE OUTPUTS



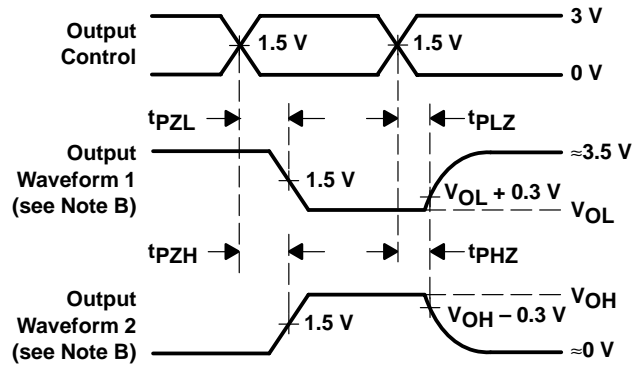
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT652ATQCT	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT652A	Samples
CY74FCT652ATSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT652A	Samples
CY74FCT652ATSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT652A	Samples
CY74FCT652CTQCT	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT652C	Samples
CY74FCT652CTSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT652C	Samples
CY74FCT652TQCT	ACTIVE	SSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT652	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT652ATQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT652ATSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT652CTQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT652CTSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT652TQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

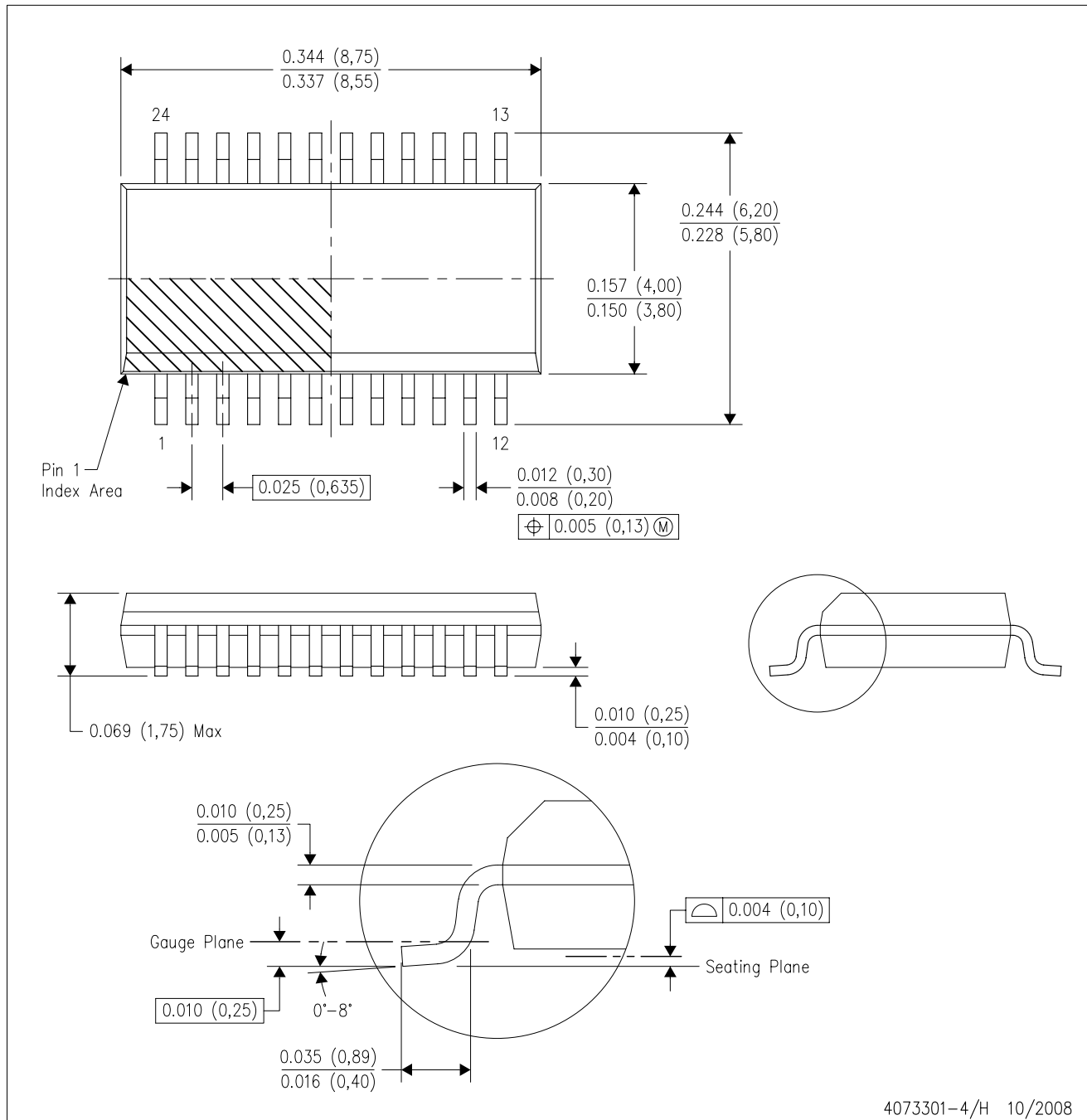
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT652ATQCT	SSOP	DBQ	24	2500	367.0	367.0	38.0
CY74FCT652ATSOCT	SOIC	DW	24	2000	350.0	350.0	43.0
CY74FCT652CTQCT	SSOP	DBQ	24	2500	367.0	367.0	38.0
CY74FCT652CTSOCT	SOIC	DW	24	2000	350.0	350.0	43.0
CY74FCT652TQCT	SSOP	DBQ	24	2500	367.0	367.0	38.0

DBQ (R-PDSO-G24)

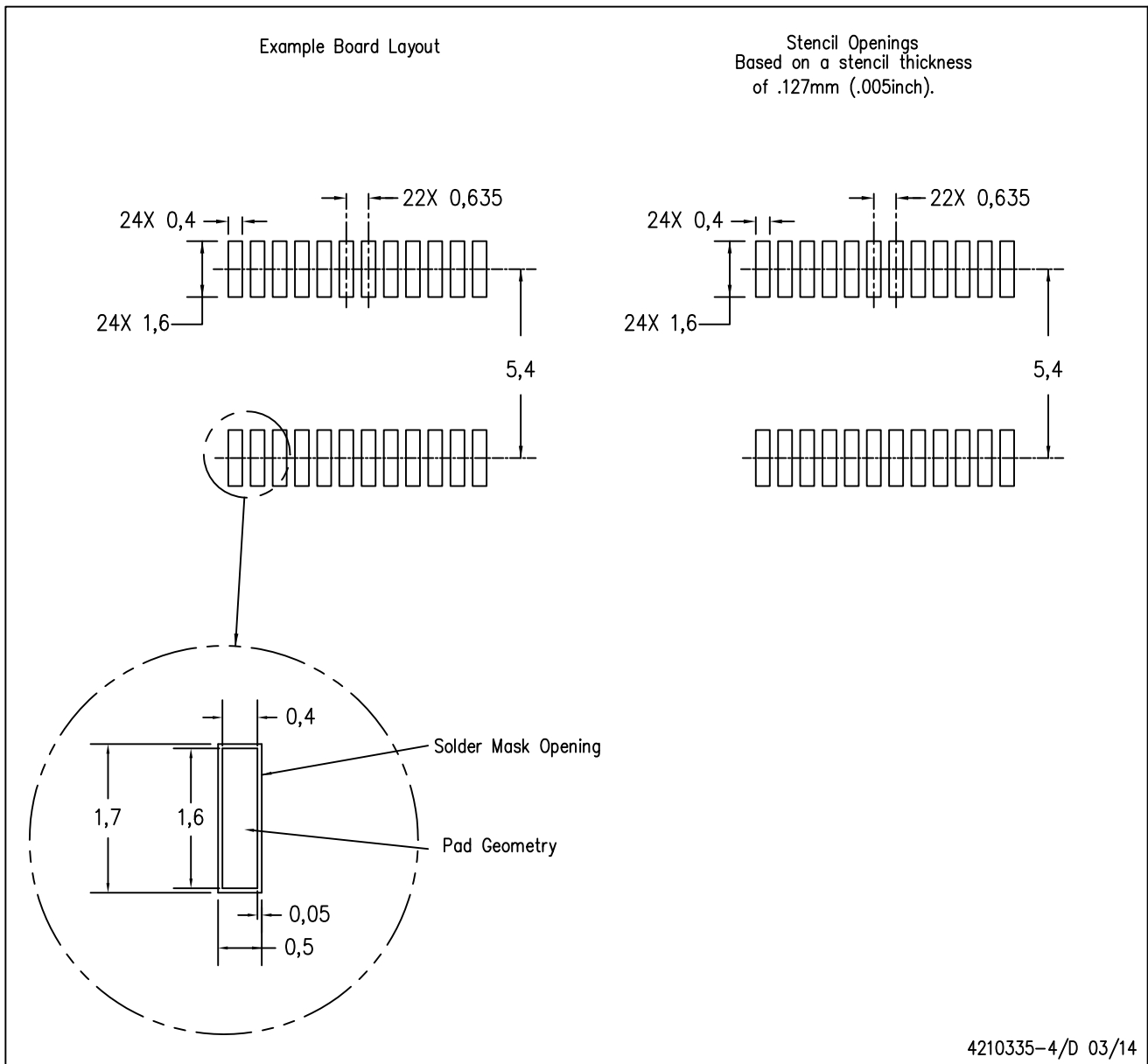
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AE.

DBQ (R-PDSO-G24)

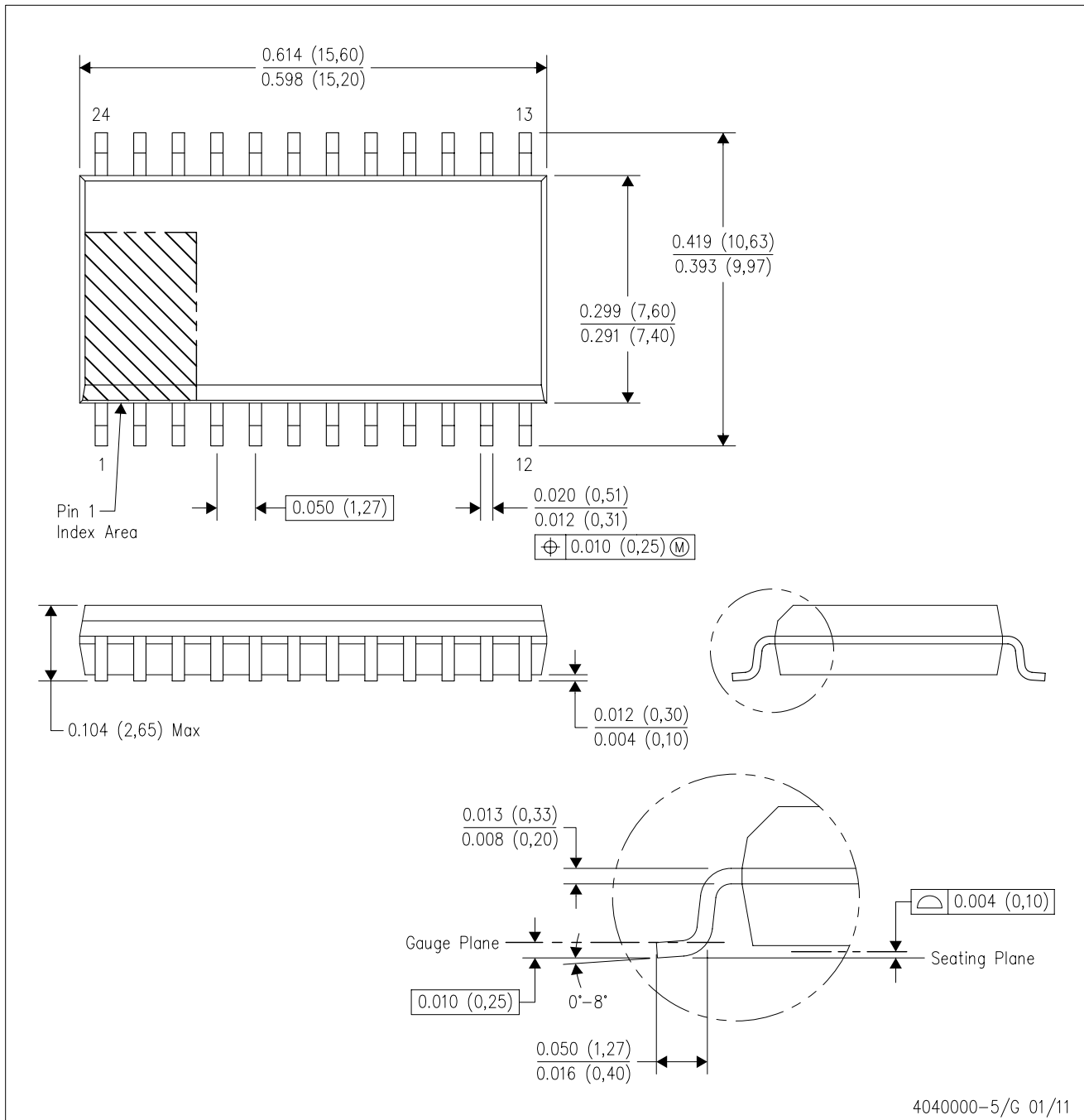
PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AD.

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